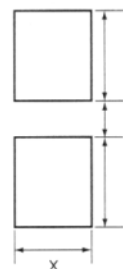


Soldering Method and Allowable Range of Reflow

Soldering Method	Allowable Range of Reflow
Hot-Plate Reflow	<p>Peak Temp. at Capacitor Terminal (°C)</p> <p>Reflow Time (second)</p>
Infrared-Ray Reflow Air Reflow	<p>Peak Temp. at Capacitor Top (°C)</p> <p>Reflow Time (second)</p>

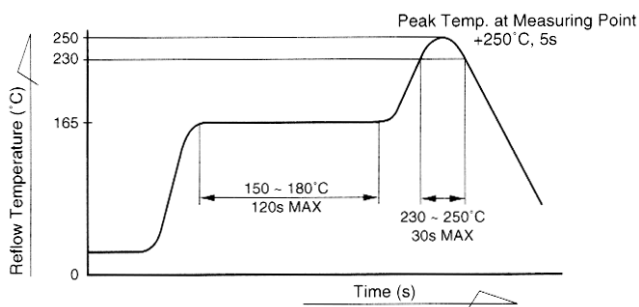
Recommended Land Size



Size	X	Y	a
φ3	1.6	2.2	0.8
φ4	1.6	2.6	1.0
φ5	1.6	3.0	1.4
φ6.3	1.6	3.5	2.1
φ3×5.5L, φ8×6.2L, φ8×7L	2.5	4.0	2.1
φ8×10L	2.5	3.5	3.0
φ10×8L, φ10×10L	2.5	4.0	4.0

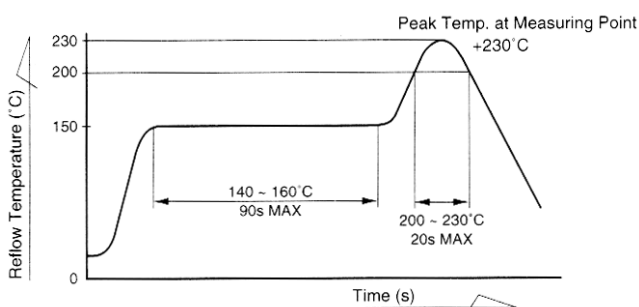
Soldering by Reflow

● Chip Type Aluminum Electrolytic Capacitors (Lead-Free product)



- Pre-heating shall be done at +150 ~180 and for 120 second.
- The temperature at capacitor top shall not exceed +250 .
- The duration for over +230 temperature at capacitor top shall not exceed 30 seconds.
- Reflow shall be done within 2 cycles. Please make sure the parts have enough cooling down time between the first and second soldering process.
- The standard temperature profile differs by every reflow method.
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.
- Please contact us for the applicable product series.
- Please contact us for the UU series.

● Chip Type Aluminum Electrolytic Capacitors (Conventional product)



- Pre-heating shall be done at +140 ~160 and for 90 second (less than 120 seconds for φ12.5 or larger chips.)
- The temperature at capacitor top shall not exceed +230 .
- The duration for over +200 temperature at capacitor top shall not exceed 20 seconds.
- The standard temperature profile differs by every reflow method.
- Please contact us if capacitors are subject to the conditions other than the allowable range of reflow.
- Reflow shall be done within 2 cycles. Please make sure the parts have enough cooling down time between the first and second soldering process.